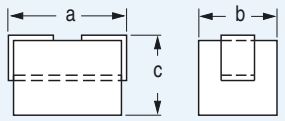
EMI-suppression products

SMD beads



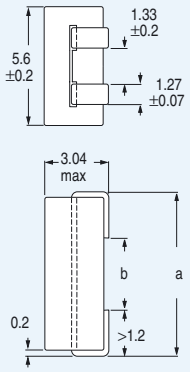
BDS3/1.8/5.3-3S1		
a	b	c
5.3 ± 0.35	3.05 ± 0.15	1.8 max
|Z| typ = 28 Ω (10 MHz) 1)		
BDS3/1.8/5.3-4S2		
a	b	c
5.3 ± 0.35	3.05 ± 0.15	1.8 max
|Z| typ = 38 Ω (100 MHz) 1)		
BDS3/3/4.6-3S1		
a	b	c
4.6 ± 0.3	3.05 ± 0.15	3 max
|Z| typ = 45 Ω (10 MHz) 1)		
BDS3/3/4.6-4S2		
a	b	c
4.6 ± 0.3	3.05 ± 0.15	3 max
|Z| typ = 50 Ω (100 MHz) 1)		
BDS3/3/8.9-3S1		
a	b	c
8.9 ± 0.35	3.05 ± 0.15	3 max
|Z| typ = 80 Ω (10 MHz) 2)		
BDS4.6/3/8.9-4S2		
a	b	c
8.9 ± 0.35	4.6 ± 0.3	3 max
|Z| typ = 100 Ω (100 MHz) 2)		

Our range of SMD beads replace the well known beads on wire in applications where SMD components are required.
They consist of a rectangular ferrite body and a lenght of flat copper wire, which is inserted through the ferrite and bent around to form two solder pads. The wire is presoldered and complies with solderability test TA (method 1) in IEC 60068-2-58.

Taping method IEC 60286-3, EIA 481-1 and 481-2.

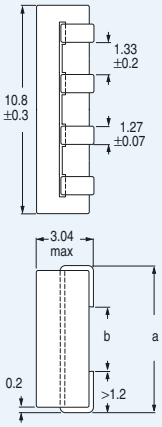
1) DC resistance < 0.6 mΩ
2) DC resistance < 1.0 mΩ

SMD common mode chokes



CMS2-5.6/3/4.8-4S2
a = 4.75 ± 0.3 and b > 1.1
|Z| typ = 35 Ω (100 MHz)
CMS2-5.6/3/8.9-4S2
a = 8.9 – 0.5 and b > 5
|Z| typ = 60 Ω (100 MHz)

In SMD Common mode chokes 2 or 4 conductors within a single soft-ferrite block are connected along their lengths by an air gap. Common-mode signals - interference signals passing in the same direction along the input and output channels of a device (an IC for instance) - reinforce the magnetic flux around both conductors, and are therefore attenuated. In contrast, the wanted signal passing along the input and output channels cancel the flux around the conductors and therefore passes unattenuated.



CMS4-11/3/4.8-4S2	
a = 4.75 ± 0.3 and b > 1.1	
inner channel	|Z| typ = 23 Ω (100 MHz)
outer channel	|Z| typ = 30 Ω (100 MHz)
CMS4-11/3/8.9-4S2	
a = 8.9 – 0.5 and b > 5	
inner channel	|Z| typ = 45 Ω (100 MHz)
outer channel	|Z| typ = 60 Ω (100 MHz)

The wire is presoldered and complies with solderability test TA (method 1) in IEC 60068-2-58.

Taping method IEC 60286-3, EIA 481-1-A and 481-2.